



Material Content Data Sheet



Sales Product Name		BSC0910NDI		Issued		25. September 2017		
MA#		MA001092620						
Package		PG-TISON-8-3		Weight*		101.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.059	1.04	1.04	10397	10397
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		101	
	non noble metal	zinc	7440-66-6	0.041	0.04		403	
	non noble metal	iron	7439-89-6	0.822	0.81		8068	
wire	non noble metal	copper	7440-50-8	33.360	32.76	33.62	327598	336170
	noble metal	gold	7440-57-5	0.068	0.07	0.07	671	671
	encapsulation	organic material	carbon black	1333-86-4	0.092	0.09		901
plastics	plastics	epoxy resin	-	4.724	4.64		46388	
	inorganic material	silicondioxide	60676-86-0	41.047	40.30	45.03	403078	450367
	leadfinish	non noble metal	tin	7440-31-5	1.122	1.10	1.10	11016
plating	noble metal	silver	7440-22-4	0.186	0.18	0.18	1824	1824
solder	noble metal	silver	7440-22-4	0.041	0.04		399	
	non noble metal	tin	7440-31-5	0.032	0.03		319	
	non noble metal	lead	7439-92-1	1.551	1.52	1.59	15231	15949
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.01		52	
	non noble metal	zinc	7440-66-6	0.021	0.02		208	
	non noble metal	iron	7439-89-6	0.424	0.42		4167	
	non noble metal	copper	7440-50-8	17.228	16.92	17.37	169179	173606
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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